Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

HP Engage Flex Pro-C

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>250W EPA92 RPOSIL18</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at EL-MF877-01
Components, parts and materials containing refractory ceramic fibers
Components, parts and materials containing radioactive substances

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel.(see Figure 1 below)
2. Remove the Front panel from chassis.(see Figure 2-3 below)
3. Disconnect ODD SATA power cable and SATA data cable from ODD.(see Figure 4-7 below)
4. Remove the ODD from ODD cage.(see Figure 8-9 below)
5. Disconnect HDD SATA power cable and SATA data cable from HDD.(see Figure 10-11 below)
6. Remove the HDD from chassis.(see Figure 12-13 below)
7. Disconnect SATA power/data cable from MB and remove them from the chassis.(see Figure 14-17 below)
8. Disconnect PSU cable from MB. (see Figure 18-20 below)
9. Disconnect FIO cable from MB and remove FIO from chassis.(see Figure 21-24 below)
10. Remove PS2&Audio from chassis.(see Figure 25-26 below)
11. Remove the memory from the MB .(see Figure 27 below)
12. Remove speaker from chassis.(see Figure 28-29 below)
13. Remove fan duct from NB.(see Figure 30 below)
14. Remove heatsink from MB.(see Figure 31 below)
15. Remove the CPU from MB.(see Figure 32-33 below)
16. Disconnect fan cable from MB.(see Figure 34 below)
17. Remove the battery from MB.(see Figure 35 below)
18. Remove the MB from chassis.(see Figure 36-38 below)
19. Remove the fan from chassis.(see Figure 39 below)
20. Remove the PSU from chassis.(see Figure 40 below)
21. Separate the fan and fan duct.(see Figure 41-42 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the access panel

Figure 2 Use T-15 screwdriver to loose the screw

Figure 3 Remove the mail panel from the chassis

Figure 4 Rotate up the ODD cage
Figure 9 Remove ODD from the ODD cage

Figure 10 Disconnect SATA data cable from the HDD

Figure 11 Disconnect SATA power cable from the HDD

Figure 12 Press the latch and push the HDD

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Figure 13 Remove HDD from the chassis

Figure 14 Disconnect ODD SATA data cable from MB

Figure 15 Disconnect HDD SATA data cable from MB

Figure 16 Disconnect SATA power cable from MB
Figure 17 SATA cable go through the hole

Figure 18 Disconnect PSU P3 cable from MB

Figure 19 Disconnect PSU P1 cable from MB

Figure 20 Disconnect PSU P2 cable from MB

PSG instructions for this template are available at EL-MF877-01
Figure 21 Disconnect Power switch & LED cable from MB

Figure 22 Disconnect USB3.1 cable from MB

Figure 23 Use T-15 screwdriver to loose the screw of FIO

Figure 24 Remove the FIO from the chassis

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Figure 25 Disconnect the PS/2 & Audio cable from MB

Figure 26 Use T-15 screwdriver to loose the screw of PS/2 & Audio and remove it from MB

Figure 27 Remove memory from MB

Figure 28 Disconnect speaker cable from MB
Figure 29 Use T-15 screwdriver to loose the screw of speaker and remove it from chassis

Figure 30 Remove the fan duct from MB

Figure 31 Use T-15 screwdriver to loose the screw of heatsink and remove it from MB

Figure 32 Press the latch
Figure 33 Remove the CPU from MB

Figure 34 Disconnect the fan cable from MB

Figure 35 Remove the battery from MB

Figure 36 Loose the latch
Figure 37 Use T-15 screwdriver to loose the screw of MB

Figure 38 Remove the MB from chassis

Figure 39 Remove the fan from chassis

Figure 40 Remove the PSU along the rail
Figure 41 Use PH1 screwdriver to loosen the screw of fan and fan duct

Figure 42 Separate the fan and fan duct

Figure 43 De-screw from the PSU's left side, use tool #1

Figure 44 De-screw from the PSU's right side, use tool #1
Figure 45 De-screw from the PSU's left side, use tool #1

Figure 46 Remove the case top

Figure 47 De-screw the PCBA from its 4 corners, use tool #1, then pull-up the connector of AC & Fan wire

Figure 48 Remove the PCBA

Figure 49 Cut-off the biggest electrolyte-capacitor from PCBA location C1 for treatment, use tool #2

Figure 50 Select the large printed circuit board for treatment